Rochel Salt type Semi-Additive Electroless Copper Plate for IC Package

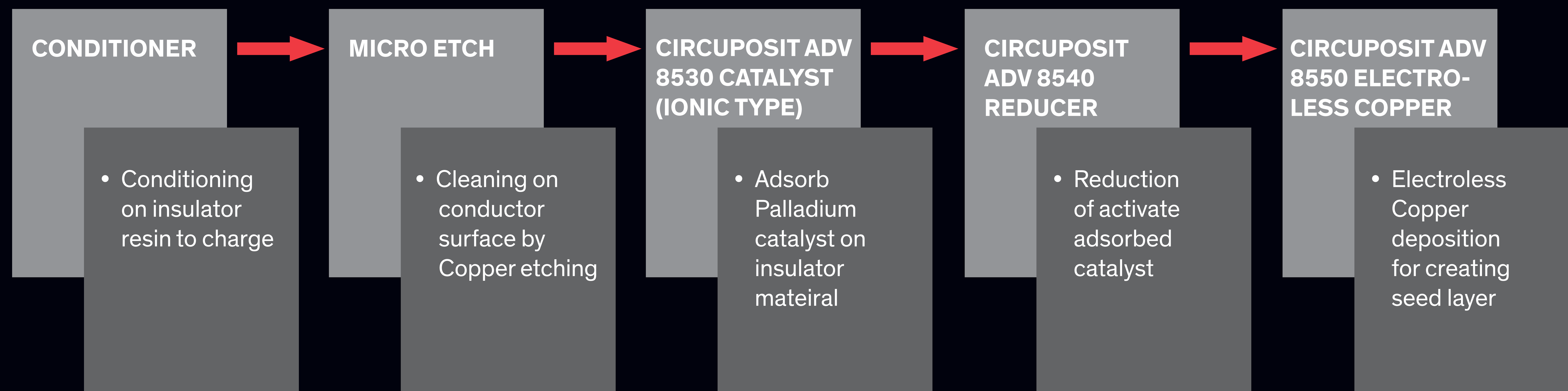
酒石酸系化学沉铜应用于IC载板半加成制程的解决方案

CIRCUPOSIT™ ADV 8550 ELECTROLESS COPPER

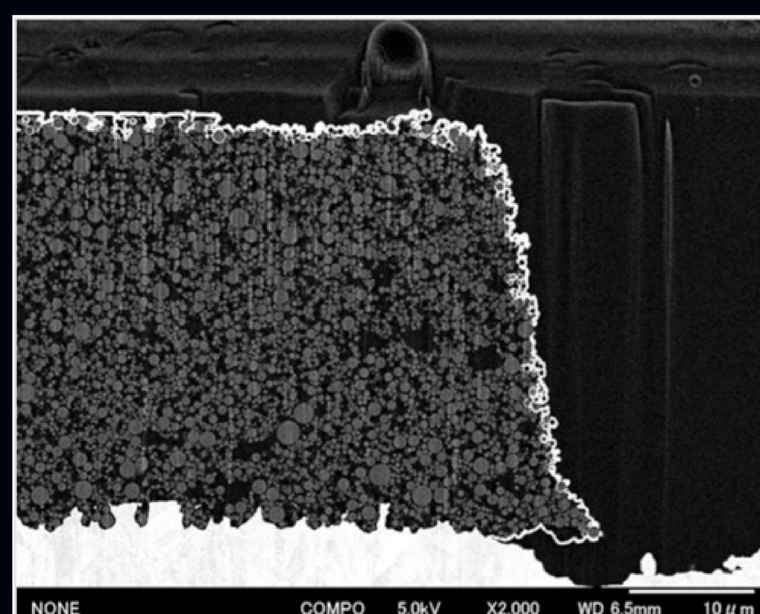
Advantage of Process:
新制程具备以下卓越之特性：

- Rochel salt type E'less Cu plate for Semi-Additive Process (EDTA free)
  针对半加成制程所开发的酒石酸系化学沉铜（EDTA free）
- Applying Alkaline Ionic Catalyst system which does not require PRE-DIP solution
  可搭配新开发的碱性离子钯系统，且不需要预浸流程
- High speed deposition with excellent bath stability
  沉积速率快且槽液稳定性亦高
- Pure Copper metal deposition without affect to for Flash etching speed
  纯铜金属沉积，不影响后段线路蚀刻速率

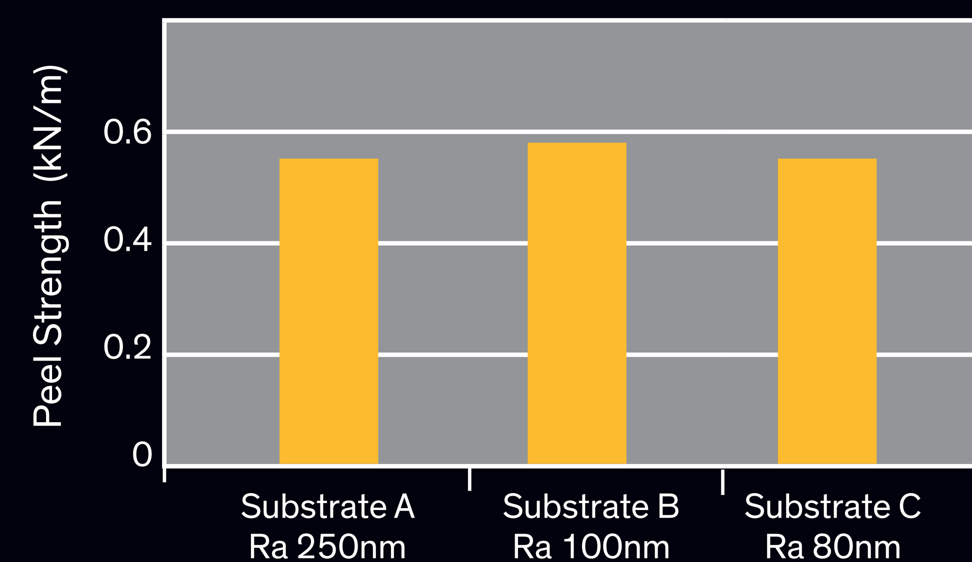
Process sequence:
制程之流程：



Excellent Plating uniformity on Microvia
优良的沉积均匀度于盲孔内



Stable adhesion on Low Ra insulator materials
即使在低Ra值的表面，
仍具有优异且稳定的附着力表现。



Achieve excellent bath stability with high deposition speed with Rochel salt base E'less Copper plate bath formulation
新酒石酸型化学铜，其沉积速率快且槽液稳定性亦高

Less bath decomposition after 72hr aging

Form No. 886-01654

® ™ Trademarks of The Dow Chemical Company ("Dow") or an affiliated company of Dow